

SANYO Semiconductors DATA SHEET

LV51138T — 2-Cell Lithium-Ion Secondary Battery Protection IC

Overview

The LV51138T is a protection IC for 2-cell lithium-ion secondary batteries.

Features

• High detection voltage accuracy:

• Discharge current monitoring function:

• Monitoring function for each cell: Detects overcharge and over-discharge conditions and controls the

charging and discharging operation of each cell. Over-charge detection accuracy ±25mV

Over-discharge detection accuracy $\pm 100 \text{mV}$ • Hysteresis cancel function: The hysteresis of over-discharge detection voltage is made small by

sensing the connection of a load after overcharging has been detected.

Detects over-currents, load shorting, and excessively high voltage of a

charger and regulates charging and discharging operations.

• Low current consumption: Normal operation mode typ. 6.0μA

Stand by mode max. 0.2µA

• 0V cell charging function: Charging is enabled even when the cell voltage is 0V by giving a

potential difference between the $\ensuremath{V_{DD}}$ pin and $\ensuremath{V^{\text{-}}}$ pin.

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Specifications

Absolute Maximum Ratings at Ta = 25°C

Parameter		Symbol	Conditions	Ratings	Unit
Power supply voltage		V_{DD}		-0.3 to +12	V
Input voltage Charger minus voltage		V-		V _{DD} -28 to V _{DD} +0.3	٧
Output voltage	Cout pin voltage	Vcout		V _{DD} -28 to V _{DD} +0.3	V
	Dout pin voltage	Vdout		V _{SS} -0.3 to V _{DD} +0.3	V
Allowable power dissipation		Pd max	Independent IC	170	mW
Operating ambient temperature		Topr		-30 to +85	°C
Storage temperature		Tstg		-40 to +125	°C

Electrical Characteristics at Ta = 25°C, unless especially specified.

Parameter	Symbol	Conditions		Ratings		
- diamotol			min	typ	max	Unit
Operation input voltage	Vcell	Between V _{DD} and V _{SS}	1.5		10	V
0V cell charging minimum operation voltage	Vmin	Between V _{DD} -V _{SS} =0 and V _{DD} -V ⁻			1.5	V
Over-charge detection voltage	Vd1		4.185	4.210	4.235	V
		Ta = 0°C to 45°C *2	4.175	4.210	4.245	V
Over-charge reset voltage	Vh1	VM ≤ Vd3	4.000	4.050	4.100	V
		VM > Vd3	4.110		4.220	V
Over-charge detection delay time	td1	V _{DD} -Vc=3.5V→4.5V, Vc-V _{SS} =3.5V	0.5	1.0	1.5	s
Over-charge reset delay time	tr1	V _{DD} -Vc=4.5V→3.5V, Vc-V _{SS} =3.5V	20.0	40.0	60.0	ms
Over-discharge detection voltage	Vd2		2.20	2.30	2.40	V
Over-discharge reset hysteresis voltage	Vh2		10.0	20.0	40.0	mV
Over-discharge detection delay time	td2	V _{DD} -Vc=3.5V→2.2V, Vc-V _{SS} =3.5V	50	100	150	ms
Over-discharge reset delay time	tr2	V _{DD} -Vc=2.2V→3.5V, Vc-V _{SS} =3.5V	0.5	1.0	1.5	ms
Over-current detection voltage	Vd3	V _{DD} -Vc=3.5V, Vc-V _{SS} =3.5V	0.180	0.200	0.220	V
Over-current reset hysteresis voltage	Vh3	V _{DD} -Vc=3.5V, Vc-V _{SS} =3.5V	5.0	10.0	20.0	mV
Over-current detection delay time	td3	V _{DD} -Vc=3.5V, Vc-V _{SS} =3.5V	10.0	20.0	30.0	ms
Over-current reset delay time	tr3	V _{DD} -Vc=3.5V, Vc-V _{SS} =3.5V	0.5	1.0	1.5	ms
Short circuit detection voltage	Vd4	V _{DD} -Vc=3.5V, Vc-V _{SS} =3.5V	1.0	1.3	1.6	V
Short circuit detection delay time	td4	V _{DD} -Vc=3.5V, Vc-V _{SS} =3.5V	0.4	1.0	1.6	ms
Over-charger detection voltage	Vd5	Between V _{DD} -Vc=3.5V, Vc-V _{SS} =3.5V (V ⁻)-V _{SS}	-0.60	-0.45	-0.30	٧
Overcharge reset hysteresis voltage	Vh5	V _{DD} -Vc=3.5V, Vc-V _{SS} =3.5V	25.0	60.0	100.0	mV
Standby reset voltage	Vstb	Between V _{DD} -Vc=2.0V, Vc-V _{SS} =2.0V (V ⁻)-V _{SS}	V _{DD} ×0.4	V _{DD} ×0.5	V _{DD} ×0.6	٧
Excessively high voltage charger detection delay time	td5	V _{DD} -Vc=3.5V, Vc-V _{SS} =3.5V *1	0.5	1.5	3.0	ms
Excessively high voltage charger reset delay time	tr5	V _{DD} -Vc=3.5V, Vc-V _{SS} =3.5V	0.5	1.5	3.0	ms
Reset resistance (connected to V _{DD})	R_{DD}		100	200	400	kΩ
Reset resistance (connected to $V_{\mbox{SS}}$)	R _{SS}		15	30	60	kΩ
Cout Nch ON voltage	V _O L1	I _O L=50μA, V _{DD} -Vc=4.4V, Vc-V _{SS} =4.4V			0.5	V
Cout Pch ON voltage	V _O H1	I _O L=50μA, V _{DD} -Vc=3.9V, Vc-V _{SS} =3.9V	V _{DD} -0.5			V
Dout Nch ON voltage	V _O L2	I _O L=50μA, V _{DD} -Vc=2.2V, Vc-V _{SS} =2.2V			0.5	V
Dout Pch ON voltage	V _O H2	I _O L=50μA, V _{DD} -Vc=3.9V, Vc-V _{SS} =3.9V	V _{DD} -0.5			V
Vc input current	lvc	V _{DD} -Vc=3.5V, Vc-V _{SS} =3.5V		0.0	1.0	μА
Current drain	I _{DD}	V _{DD} -Vc=3.5V, Vc-V _{SS} =3.5V		6.0	13.0	μА
Standby current	Istb	V _{DD} -Vc=2.2V, Vc-V _{SS} =3.5V			0.2	μА
T-terminal input ON voltage	Vtest	V _{DD} -Vc=3.5V, Vc-V _{SS} =3.5V	V _{DD} ×0.4	V _{DD} ×0.5	V _{DD} ×0.6	V

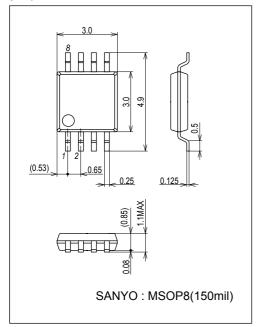
 $^{^{\}star}1$: Upon connecting to charger upon over-discharge, the delay time after recovery from over-discharge.

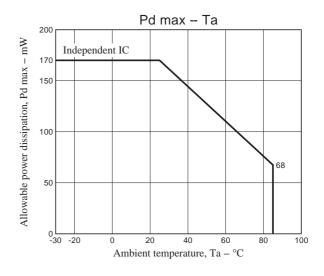
^{*2 :} The ratings in the temperature range of the table above are design target values and are not tested at the time of shipment.

Package Dimensions

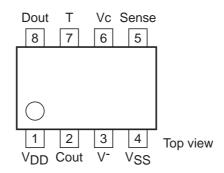
unit : mm (typ)

3245B





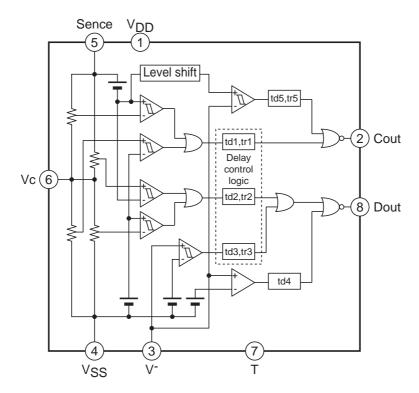
Pin Assignment



Pin Functions

Pin No.	Symbol	Description	
1	V_{DD}	V _{DD} pin	
2	Cout	Overcharge detection output pin	
3	V-	Charger minus voltage input pin	
4	V _{SS}	V _{SS} pin	
5	Sense	Sense pin	
6	Vc	Intermediate voltage input pin	
7	Т	Pin to shorten detection time ("H":Shortening mode, "L":Normal mode)	
8	Dout	Overdischarge detection output pin	

Block Diagram



Functional Description

Over-charge detection

If either of the cell voltage is equal to or more than the over-charge detection voltage, stop further charging by turning "L" the Cout pin and turning off external Nch MOS FET after the over-charge detection delay time. This delay time is set by the internal counter.

The over-charge detection comparator has the hysteresis function. Note that this hysteresis can be cancelled by connecting the load after detection of over-charge detection, and it becomes small to hysteresis peculiar to a comparator.

Over-charge release

If both cell voltages become equal to or less than the over-charge release voltage ($VM \le Vd3$) when charger is connected, or if it become equal to or less than the over-charge release voltage (VM > Vd3) when load is connected, the Cout pin returns to "H" after the over-charge release delay time set by the internal counter.

When load is connected and either cell or both cell voltages are equal to or more than the over-charge release voltage (VM > Vd3), the Cout pin does not return to "H". But the load current flows through the parasitic diode of external Nch MOS FET on Cout, consequently each cell voltage becomes equal to or less than over-charge release voltage, (VM > Vd3) the Cout pin returns to "H." after the over-charge release delay time.

However, excessive voltage charger is connected as mentioned below, Cout pin does not return to "H" because excessive charger detection starts after over-charge release operation.

Over-discharge detection

When either cell voltage is equal to or less than over-discharge voltage, the IC stops further discharging by turning the Dout pin "L" and turning off external Nch MOS FET after the over-charge detection delay time.

The IC goes into stand-by mode after detecting over-discharge and its consumption current is kept at about 0A. After over-discharge detection, the V⁻ pin will be connected to V_{DD} pin via internal resistor (typ 200k Ω).

Over-discharge release

Release from over-discharge is made by only connecting charger. If the V^- pin voltage becomes equal to or lower than the stand-by release voltage by connecting charger after detecting over-discharge, The IC is released from the stand-by state to start cell voltage monitoring. If both cell voltages become equal to or more than the over-discharge detection voltage by charging, the Dout pin returns to "H" after the over-discharge release delay time set by the internal counter.

Over-current detection

When excessive current flows through the battery, the V- pin voltage rises by the ON resister of external MOS FET and becomes equal to or more than the over-current detection voltage, the Dout pin turns to "L" after the over-current detection delay time and the external Nch MOS FET is turned off to prevent excessive current in the circuit. The detection delay time is set by the internal counter. After detection, the V- pin will be connected to V_{SS} via internal resistor (typ $30k\Omega$). It will not go into stand-by mode after detecting over-current.

Short circuit detection

If greater discharging current flows through the battery and the V- pin voltage becomes equal to or more than the short-circuit detection voltage, it will go into short-circuit detection state after the short circuit delay time shorter than the over-current detection delay time. When short-circuit is detected, just like the time of over-current detection, the Dout pin turns to "L" and external Nch MOS FET is turned off to prevent high current in the circuit. The V- pin will be connected to V_{SS} after detection via internal resistor (typ. $30k\Omega$). It will not go into stand-by mode after detecting short circuit.

Over-current/short-detection release

After detecting over-current or short circuit, the internal resistor (typ. $30k\Omega$) between V- pin and VSS pin becomes effective. If the load resistor is removed, the V- pin voltage will be pulled down to the VSS level. Thereafter, the IC will be released from the over-current/short-circuit detection state when the V- pin voltage becomes equal to or less than the over-current detection voltage, and the Dout pin returns to "H" after over-current release delay time set by the internal counter.

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Excessive charger detection/release

If the voltage between V- pin and VSS pin becomes equal to or less than the excessive charger detection voltage by connecting a charger, no charging can be made by turning the Cout pin "L" after delay time and turning off the external Nch MOS FET. If that voltage returns to equal to or more than the excessive charger detection voltage during detection delay time, the excessive charger detection will be stopped. If the voltage between V- pin and VSS pin becomes equal to or more than the excessive charger detection voltage after excessive charger detection, the Cout returns to "H" after delay time. The detection/return delay time is set internally.

If Dout pin is "L", charging will be made through the parasitic diode of external Nch FET on Dout pin. In that case, the voltage between V- pin and VSS pin is nearly -Vf which is less than the over-charger detection voltage, therefore no excessive charger detection will be made during over-discharge, over-current and short-circuit detection. Furthermore, if excessive voltage charger is connected to the over-discharged battery, no excessive charger detection is made while the Dout pin is "L". But the battery is continued charging through the parasitic diode. If the battery voltage rises to the over-discharge detection voltage and the voltage between V- pin and VSS pin remains equal to or less than the excessive charger detection voltage, the delay operation will be started after Dout pin turns to "H."

0V cell charging operation

If voltage between V_{DD} and V becomes equal to or more than the 0V cell charging lowest operation voltage when the cell voltage is 0V, the Cout pin turns to "H" and charging is enabled.

Shorten the test time

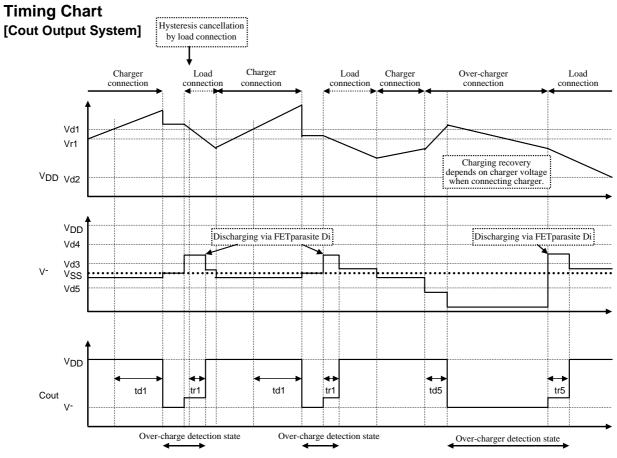
By turning T pin to the V_{DD} , the delay times set by the internal counter can be cut. If T pin is open, the delay times are normal. Delay time not set by the counter just like as short circuit detection delay cannot be controlled by this pin. And we recommend that T pin is connected to V_{SS} to prevent malfunction when excessive current flows in short circuit operation.

Operation in case of detection overlap

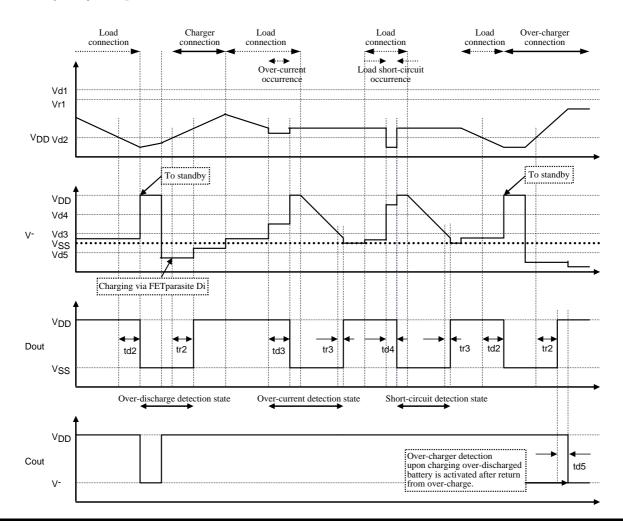
Overlap state		Operation in case of detection overlap	State after detection	
When, during over- charge detection,	Over-discharge detection is made,	Over-charge detection is preferred. If over- discharge state continues even after over- charge detection, over-discharge detection is resumed.	When over-charge detection is made first, V ⁻ is released. When over-discharge is detected after over-charge detection, the standby state is not effectuated. Note that V ⁻ is connected to V_{DD} via $200k\Omega$.	
	Over-current detection is made,	(*1) Both detections' can be made in parallel. Over-charge detection continues even when the over-current state occurs. If the over-charge state occurs first, over-current detection is interrupted.	(*2) When over-current is detected first, V ⁻ is connected to V _{SS} via 30kΩ. When over-charge detection is made first, V ⁻ is released.	
When, during over- discharge detection,	Over-charge detection is made,	Over-discharge detection is interrupted and over-charge detection is preferred. When over-discharge state continues even after over-charge detection, over-discharge detection is resumed.	The standby state is not effectuated when over-discharge detection is made after over-charge detection. Note that V- is connected to V_DD via $200 k\Omega.$	
	Over-current detection is made,	(*3) Both detections can be made in parallel. Over-discharge detection continues even when the over-current state is effectuated first. Over- current detection is interrupted when the over- discharge state is effectuated first,	(*4) If over-current is detected in advance, V will be connected to V_{SS} via 30kΩ. After detecting over-discharge, V will be connected to V_{DD} via 200kΩ to get into standby state. If over-discharge is detected in advance, V will be connected to V_{DD} via 200kΩ to get into standby state.	
When, during over- current detection,	Over-charge detection is made, Over-discharge detection is made,	(*1) (*3)	(*2) (*4)	

(Note) Short-circuit detection can be made independently.

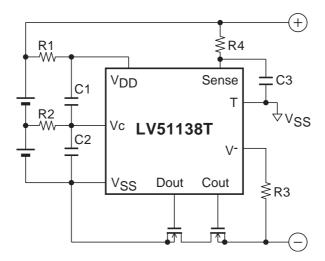
Over-charger detection does not work during over-discharge, over-current or short-circuit detection and the delay time starts after return from these states.



[Dout Output System]



Application Circuit Example



Components	omponents Recommended value		unit
R1, R2	100	1k	Ω
R3	2k	4k	Ω
R4	100	10k	Ω
C1, C2, C3	0.1μ	1μ	F

^{*} These numbers don't mean to guarantee the characteristic of the IC.

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^{*} In addition to the components in the upper diagram, it is necessary to insert a capacitor with enough capacity between VDD and VSS of the IC as near as possible to stabilize the power supply voltage to the IC.